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## RESIN SEALED SEMICONDUCTOR DEVICE

DAINIPPON PRINTING CO LTD

Inventor(s): ;YAMADA JUNICHI ;SASAKI MASARU

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**Abstract:**

**PURPOSE:** To provide a resin sealed semiconductor device which can cope with the increased number of terminals and can be reduced more in size by providing the electrode sections of semiconductor elements between inner leads and electrically connecting the electrode sections to the front ends of inner leads on the side opposite to the semiconductor element mounting side through wires.

**CONSTITUTION:** A semiconductor element 110 is mounted on and fixed to inner leads 131 with an insulating adhesive material 150 so that an electrode section (pad) 111 on the electrode section 111 side surface of the element 110 can be put between the leads 131. The electrode section 111 is electrically connected to the second surfaces 31Ab of the leads 131 at the front ends of inner lead sections 131 through wires 120. The thickness of the inner lead sections 131 is adjusted to  $40\mu\text{m}$  and the thickness of portion other than the sections 131 is maintained at the thickness of a lead frame material which is 0.15mm. The arranging pitch of the inner leads is adjusted to as narrow as 0.12mm so that the number of terminals can be increased.

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